



Revision History	
Revision	Notes
A	*** preliminary ***
C4	new layout, ceramic output caps on customer demand

- NOTES:
- 1) stress calculations for 9Vin and -2Aout
  - 2) R12 for test purposes only
  - 3) passives selected for max. height around 8mm
  - 4) D100 backpacked R3

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Orderable:	Designed for: Public Release	Mod. Date: 9/21/2020
TID #: N/A	Project Title: Synchronous Inverting Buck Boost	
Number: PMP30916	Rev: C4	Sheet Title:
SVN Rev: Not in version control	Assembly Variant: [No Variations]	Sheet: 1 of 1
Drawn By:	File: PMP30916RevC4_Schematic.schdoc	Size: B
Engineer: B.Geck	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	



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